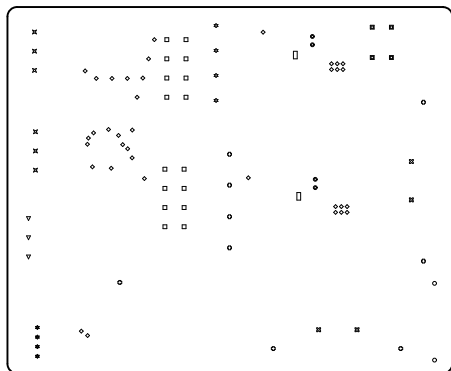




Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.8	
1	Top Layer		2.90mil		
	Dielectric 1	FR4 3P	11.40mil	4.2	
2	Signal Layer		0.40mil		
	Dielectric 2	FR4 3P	2.90mil	4.2	
3	Signal Layer 2		0.40mil		
	Dielectric 3	FR4 3P	1.40mil	4.2	
4	Bottom Layer		2.90mil		
	Bottom Solder	Solder Resist	0.40mil	3.8	
	Bottom Overlay				

[illegible]

DESIGN INFORMATION			
MIN. TRACK WIDTH:	8	ML	
MIN. CLEARANCE:	0.2	mm	
MIN. VIA PAD SIZE:	24	ML	
MINIMUM ANNULAR RING		0.05mm (2ML)	EXTERNAL
PER PC-D-275 CLASS 2 LEVEL C			
REGISTRATION TOLERANCES:	METAL	+/- 5	ML HOLES
		+/- 2	ML
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED):		+/- 3	ML

MATERIAL:			
☐ FR-408	☒	FR-4 High Tg	☐ OTHER _____
THICKNESS:	☒	62 ML (1.6mm) +/-10%	☐ OTHER _____
TOLERANCE:	☒	ANSI IPC-6012 TYPE 3 CLASS 2	
	☐	OTHER +/-	_____
BOW & TWIST:	☒	ANSI IPC-6012 TYPE 3 CLASS 2	
	☐	OTHER +/-	_____
DRILLING:			
REFERENCE:	☒	AS SHOWN	☒ NO DRILL FILES
PTH COPPER THICKNESS:	☒	20-30 um	☐ OTHER _____
BOARD FINISH:			
SULFONATE:	☒	TOP	☒ BOTTOM
SULFONATE COLOR:	☒	WHITE	☐ OTHER _____
SOLDER RESIST COLOR:	☒	GREEN	☐ OTHER _____
	☒	WHITE	☐ SEM-GLOSS
SURFACE FINISH:			
☒	IMMERSION GOLD (ENIG)	☐	ENIG
☐	MLT/IN/SILVER OR EQUIV	☐	OTHER _____
ARRAY/PANEL:			
☐	CUT AND TRIM PER MT BOARD OUTLINE	☒	V. SCORE
☐	N.C. ROUTE		
CERTIFICATION:			
MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:			
☒	ANSI IPC-A-600F CLASS ->	☐ 1	☒ 2
☐	Relis	☐	☐ 3
		☐	OTHER _____
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS. PCB MUST BEAR THE UL94-V0 UL REGISTERED MATERIAL ID NUMBER			
ADDITIONAL REQUIREMENTS:			
MICROSECTION: ☐ YES ☐ NONE ☒ REQUIRED ☐ PER ORDER			
BAKE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER			
☐ XX ML ML REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE			
☐ XX ML ML REQUIRE CONDUCTIVE FILL AND PLANARIZE			
☐ OUTER XX ML TRACES REQUIRE 80 OHM SINGLE-ENDED IMPEDANCE			
☐ LAYER 2 & 3 (INNER LAYERS) XX ML WDG, XX ML SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE			



PROJECT TITLE:

DRUG218EUN

DESIGNED FOR:

Public Release

FILE NAME:

MDI10_E2.PcbDoc

ENGINEER:

LAYOUT BY:

David Medis

ALTUM DESIGNER VERSION:

23.1.1.15